



Product Change Notification

CN-202212018F

Issue date: 26 Jan 2023

Effective date: 11 May 2023

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



Change of die, lead frame and mold compound for schottky diodes in SOD128

Change Category

<input checked="" type="checkbox"/>	<input type="checkbox"/>				
Wafer	Assembl				
Fab	y				
Process	Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test	<input checked="" type="checkbox"/> Design	
<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/> Mechanical	Location	<input type="checkbox"/> Errata	
Wafer	Assembl	Specification	<input type="checkbox"/> Test	<input type="checkbox"/>	
Fab	y	<input type="checkbox"/>	Process	Electrical	
Material	Materials	Packing/Shipping/Labelin	<input type="checkbox"/> Test	spec./Tes	
s	<input type="checkbox"/>	g	Equipmen	t	
<input type="checkbox"/>	Assembl		t	coverage	
Wafer	y				
Fab	Location				
Location					

Details of this change

The following items are changed in the affected products:

- New clip type with optimized geometry
- No silver spot on lead frame surface anymore
- Change of mold compound
- Shrinkage of die size from 960 μm^2 , 1290 μm^2 , 1520 μm^2 and 1900 μm^2 to 910 μm^2 , 1220 μm^2 , 1440 μm^2 and 1780 μm^2 , respectively
- New die design
- Datasheet parameter IFSM "non-repetitive peak forward current" is measured with half sine wave pulses instead of square wave pulses

PCN-FORM-Nexperia_CN-202212018F.xlsm:

https://qcm.nexperia.com/Document/DOC-549403/PCN-FORM-Nexperia_CN-202212018F.xlsm

SQR_SOD128_BL252.pdf: https://qcm.nexperia.com/Document/DOC-549402/SQR_SOD128_BL252.pdf

PCN-2022012018F_Change_overview-DeQuMa.xlsx:

https://qcm.nexperia.com/Document/DOC-549400/PCN-2022012018F_Change_overview-DeQuMa.xlsx

PCN-Delta-Qualification-Matrix-CN-202212018F.xlsm:

<https://qcm.nexperia.com/Document/DOC-549399/PCN-Delta-Qualification-Matrix-CN-202212018F.xlsm>

Why do we implement this change?

- Improvement of robustness and inline control during assembly process
- Adaption of lead frame surface to new die design
- Improvement of robustness against delamination of mold compound
- Increase of production capacity
- Alignment with Nexperia and world technology standards

Identification of affected products

Top Side Marking

Changed products can be identified by date code after implementation

Product availability

Production

Planned first shipment: 05 May 2023

Existing inventory will be shipped until depleted

Sample information

Samples are available upon request

Impact

No impact to the product's functionality anticipated

Data sheet revision

A new datasheet will be issued

Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 25 Feb 2023. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Additional information

[View Change Notification Online](#)

Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact you distribution partner.

About Nexperia B.V.

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